

TLP284

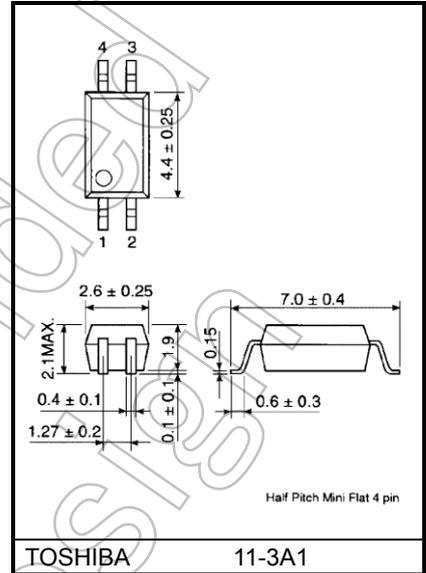
Programmable Controllers
AC/DC-Input Module
Hybrid ICs

Unit in mm

TLP284 consist of photo transistor, optically coupled to two infrared emitting diode connected inverse parallel, and can operate directly by AC input current.

Since TLP284 are guaranteed wide operating temperature ($T_a = -55$ to 110 °C) and high isolation voltage (3750 Vrms), it's suitable for high-density surface mounting applications such as programmable controllers and hybrid ICs.

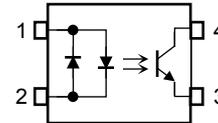
- Collector-emitter voltage : 80 V (min)
- Current transfer ratio : 50% (min)
Rank GB : 100% (min)
- Isolation voltage : 3750 Vrms (min)
- Guaranteed performance over -55 to 110 °C
- UL-recognized : UL 1577, File No.E67349
- cUL-recognized : CSA Component Acceptance Service No.5A
File No.E67349
- VDE-approved : EN 60747-5-5 (Note 1)



TOSHIBA 11-3A1

Weight: 0.05 g (typ.)

Pin Configuration (top view)



- 1 : Anode
Cathode
- 2 : Cathode
Anode
- 3 : Emitter
- 4 : Collector

Note 1: When a VDE approved type is needed, please designate the **Option(V4)**.

Construction Mechanical Rating

Creepage Distance	5.0 mm (min)
Clearance	5.0 mm (min)
Insulation Thickness	0.4 mm (min)

Start of commercial production
2008-12

Current Transfer Ratio

TYPE	Classification (Note1)	Current Transfer Ratio (%) (I_C / I_F)		Marking of Classification
		$I_F = 5 \text{ mA}, V_{CE} = 5 \text{ V}, T_a = 25^\circ\text{C}$		
		Min	Max	
TLP284	Blank	50	600	Blank, YE, GR, BL, GB
	Rank Y	50	150	YE
	Rank GR	100	300	GR
	Rank BL	200	600	BL
	Rank GB	100	600	GB, GR, BL

Note1: Ex. rank GB: TLP284 (GB)

Note: Application type name for certification test, please use standard product type name, i.e.

TLP284 (GB): TLP284

Note: For the supply status of rank Y and BL products, please contact with our sales representative.

Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

Characteristic		Symbol	Rating	Unit
LED	Forward current	$I_{F(RMS)}$	± 50	mA
	Forward current derating ($T_a \geq 75^\circ\text{C}$)	$\Delta I_F / ^\circ\text{C}$	-1.0	mA/ $^\circ\text{C}$
	Pulse forward current (Note 1)	I_{FP}	± 1	A
	Diode power dissipation	P_D	100	mW
	Diode power dissipation derating ($T_a \geq 75^\circ\text{C}$)	$\Delta P_D / ^\circ\text{C}$	-2.0	mW/ $^\circ\text{C}$
	Junction temperature	T_j	125	$^\circ\text{C}$
Detector	Collector-emitter voltage	V_{CEO}	80	V
	Emitter-collector voltage	V_{ECO}	7	V
	Collector current	I_C	50	mA
	Collector power dissipation	P_C	150	mW
	Collector power dissipation derating ($T_a \geq 25^\circ\text{C}$)	$\Delta P_C / ^\circ\text{C}$	-1.5	mW/ $^\circ\text{C}$
	Junction temperature	T_j	125	$^\circ\text{C}$
Storage temperature range		T_{stg}	-55 to 125	$^\circ\text{C}$
Operating temperature range		T_{opr}	-55 to 110	$^\circ\text{C}$
Lead soldering temperature (10 s)		T_{sol}	260	$^\circ\text{C}$
Total package power dissipation		P_T	200	mW
Total package power dissipation derating ($T_a \geq 25^\circ\text{C}$)		$\Delta P_T / ^\circ\text{C}$	-2.0	mW/ $^\circ\text{C}$
Isolation voltage (Note 2)		BV_S	3750	V _{rms}

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Pulse width $\leq 100 \mu\text{s}$, frequency 100 Hz

Note 2: AC, 60 s, R.H. $\leq 60 \%$,

Device considered a two terminal device: LED side pins shorted together and detector side pins shorted together.

Electrical Characteristics (Ta = 25°C)

Characteristic		Symbol	Test Condition	Min	Typ.	Max	Unit
LED	Forward voltage	V _F	I _F = ±10 mA	1.0	1.15	1.3	V
	Capacitance	C _T	V = 0 V, f = 1 MHz	—	60	—	pF
Detector	Collector-emitter breakdown voltage	V _{(BR)CEO}	I _C = 0.5 mA	80	—	—	V
	Emitter-collector breakdown voltage	V _{(BR)ECO}	I _E = 0.1 mA	7	—	—	V
	Collector dark current (Note 2)	I _{CEO}	V _{CE} = 48 V, Ambient light below (100 lx) (Note 1)	—	0.01 (2)	0.1 (10)	μA
			V _{CE} = 48 V, Ta = 85 °C Ambient light below (100 lx) (Note 1)	—	2 (4)	50 (50)	μA
Capacitance (collector to emitter)		C _{CE}	V = 0 V, f = 1 MHz	—	10	—	pF

Note 1: Irradiation to marking side using standard light bulb.

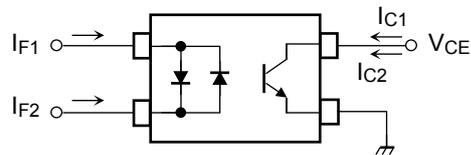
Note 2: Because of the construction, leak current might be increased by ambient light. Please use photocoupler with less ambient light.

Coupled Electrical Characteristics (Ta = 25°C)

Characteristic	Symbol	Test Condition	Min	Typ.	Max	Unit
Current transfer ratio	I _C /I _F	I _F = ±5 mA, V _{CE} = 5 V	50	—	600	%
		Rank GB	100	—	600	
Saturated CTR	I _C /I _F (sat)	I _F = ±1 mA, V _{CE} = 0.4 V	—	60	—	%
		Rank GB	30	—	—	
Collector-emitter saturation voltage	V _{CE} (sat)	I _C = 2.4 mA, I _F = ±8 mA	—	—	0.4	V
		I _C = 0.2 mA, I _F = ±1 mA	—	0.2	—	
		Rank GB	—	—	0.4	
Off-state collector current	I _C (off)	V _F = 0.7 V, V _{CE} = 48 V	—	—	10	μA
CTR symmetry	I _C (ratio)	I _C (I _F = -5 mA) / I _C (I _F = 5 mA) (Note 1)	0.33	—	3	—

Note 1:

$$I_C(\text{ratio}) = \frac{I_{C2}(I_F = I_{F2}, V_{CE} = 5V)}{I_{C1}(I_F = I_{F1}, V_{CE} = 5V)}$$



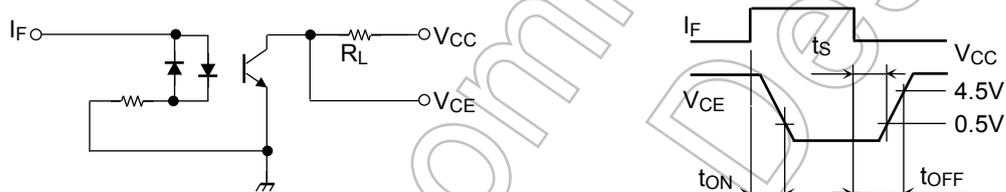
Isolation Characteristics (Ta = 25°C)

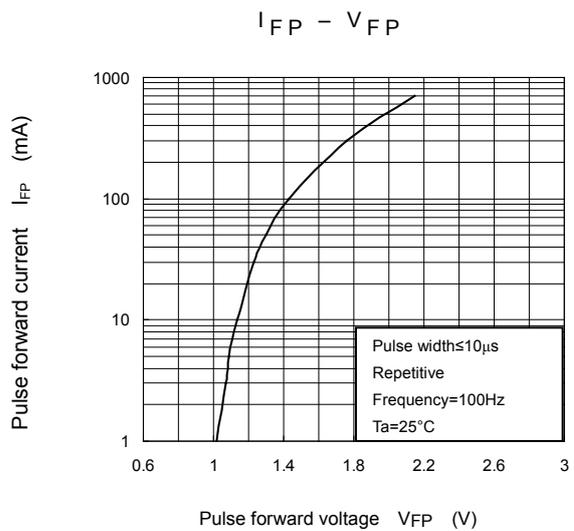
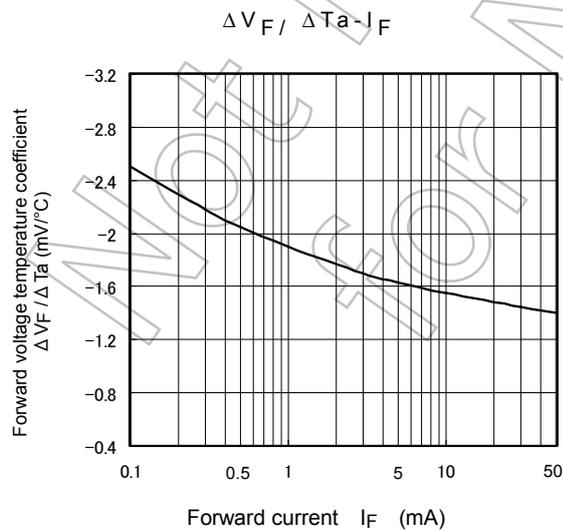
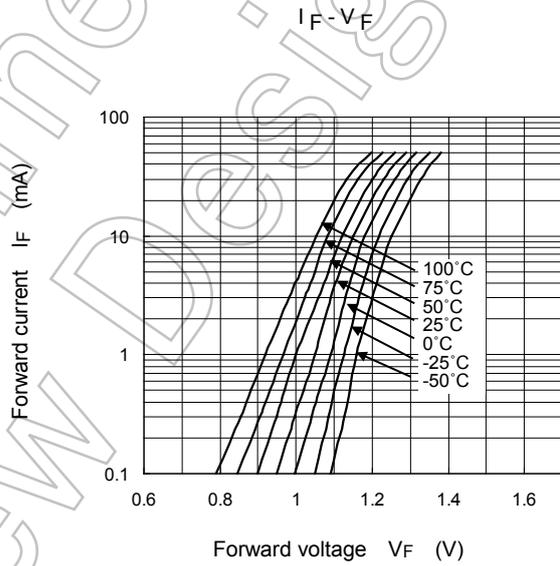
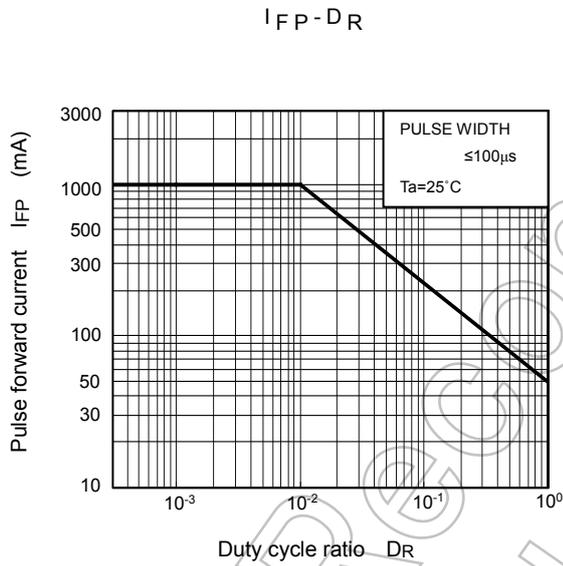
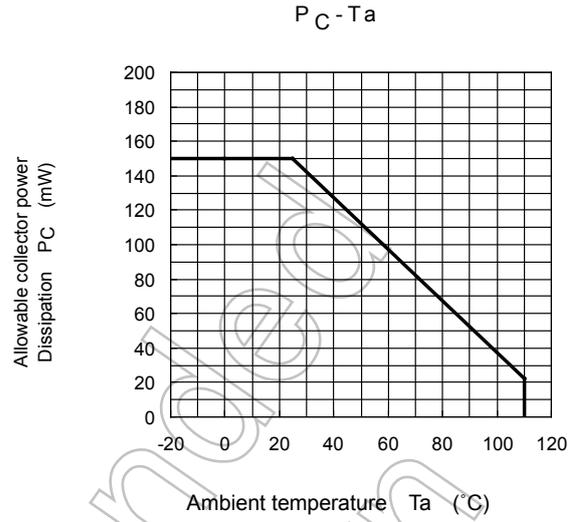
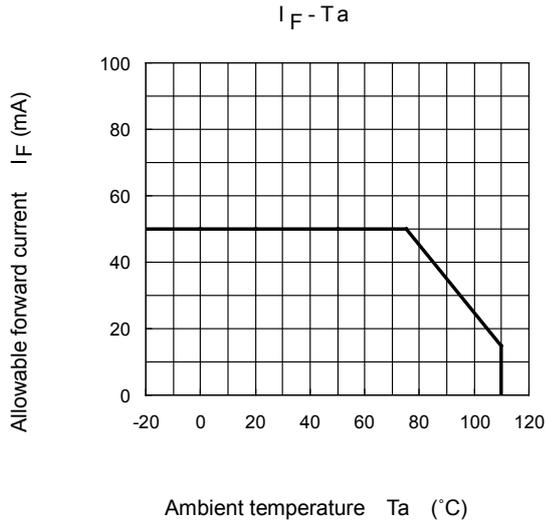
Characteristic	Symbol	Test Condition	Min	Typ.	Max	Unit
Capacitance input to output	C _S	V _S = 0 V, f = 1 MHz	—	0.8	—	pF
Isolation resistance	R _S	V _S = 500 V, R.H. ≤ 60 %	1×10 ¹²	10 ¹⁴	—	Ω
Isolation voltage	BV _S	AC, 60 s	3750	—	—	V _{rms}

Switching Characteristics (Ta = 25°C)

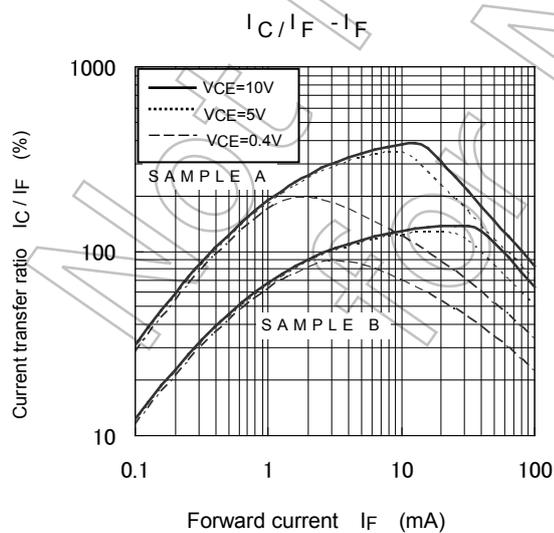
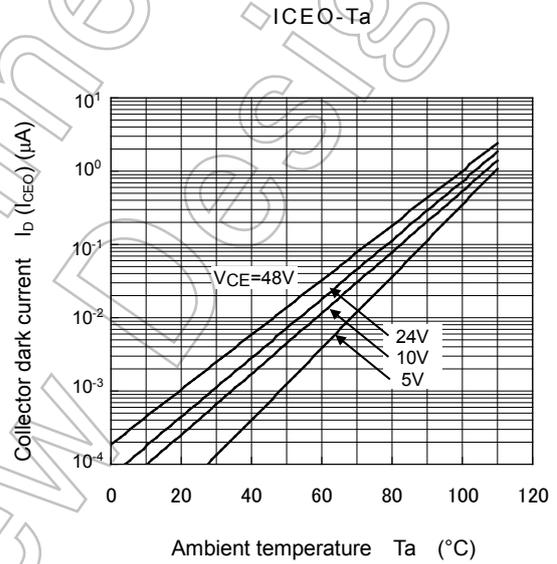
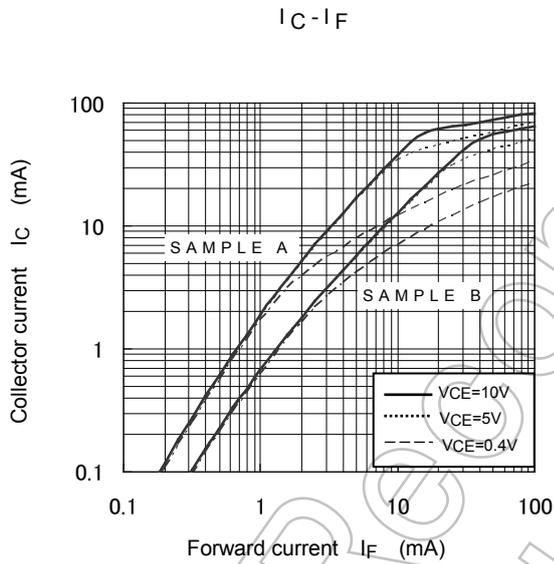
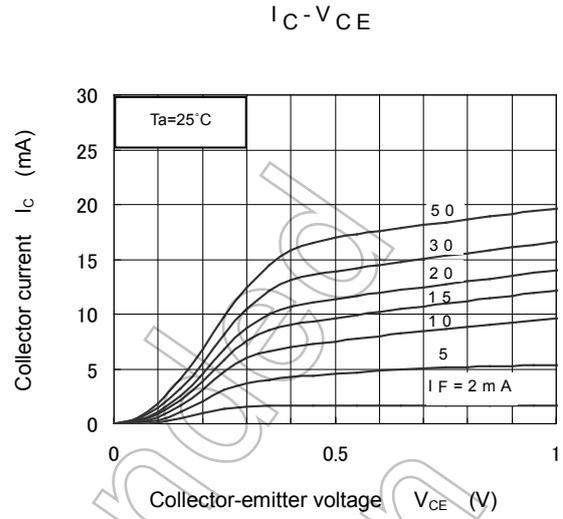
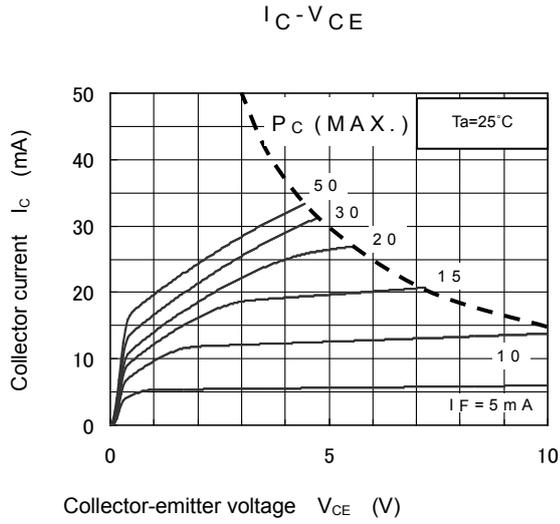
Characteristic	Symbol	Test Condition	Min	Typ.	Max	Unit
Rise time	t _r	V _{CC} = 10 V, I _C = 2 mA R _L = 100 Ω	—	2	—	μs
Fall time	t _f		—	3	—	
Turn-on time	t _{on}		—	3	—	
Turn-off time	t _{off}		—	3	—	
Turn-on time	t _{ON}	R _L = 1.9 kΩ V _{CC} = 5 V, I _F = ±16 mA (Fig.1)	—	2	—	μs
Storage time	t _s		—	25	—	
Turn-off time	t _{OFF}		—	40	—	

Fig. 1: Switching time test circuit

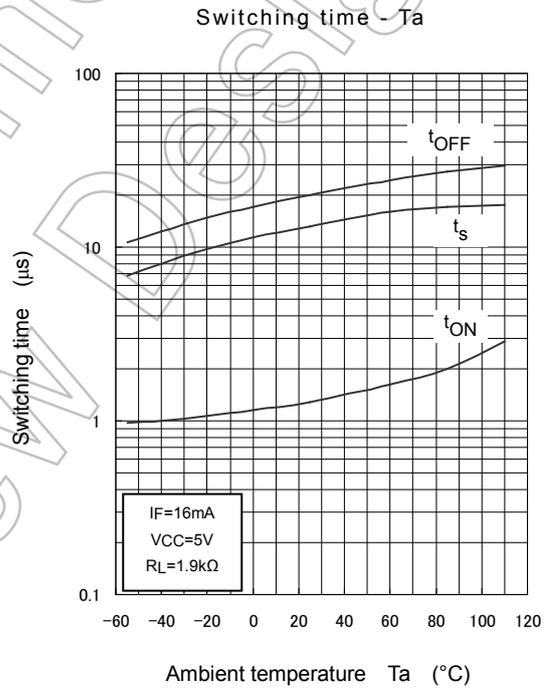
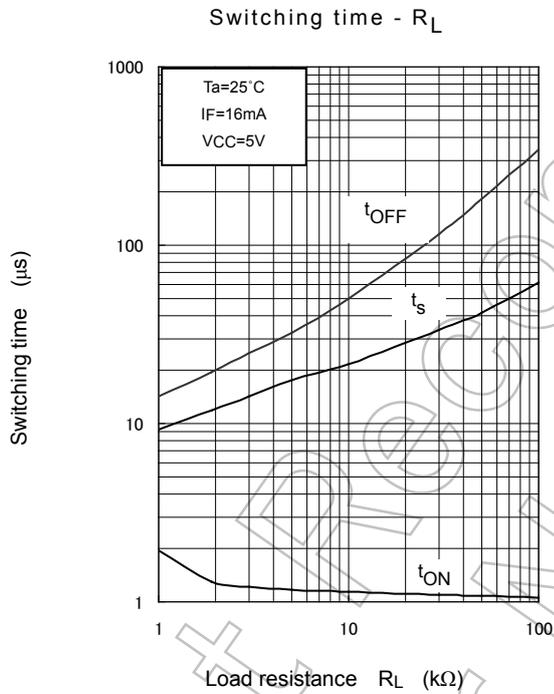
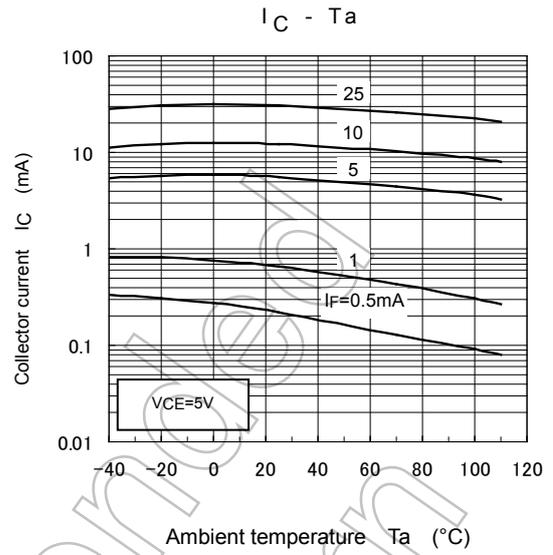
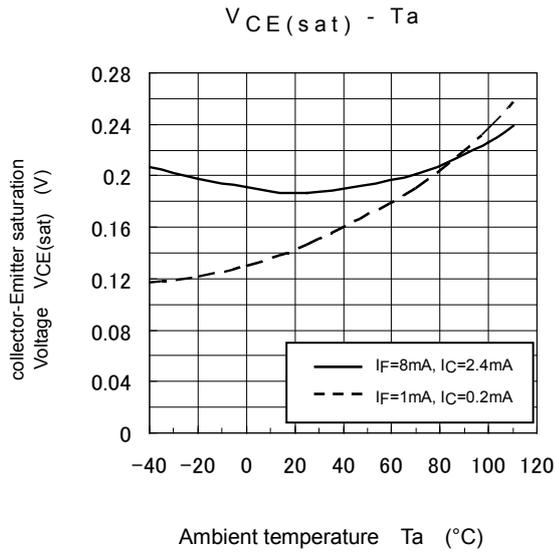




NOTE: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



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Soldering and Storage

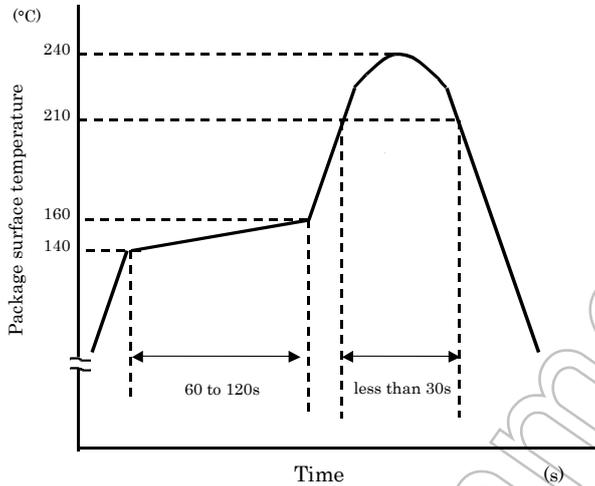
1. Soldering

1.1 Soldering

When using a soldering iron or medium infrared ray/hot air reflow, avoid a rise in device temperature as much as possible by observing the following conditions.

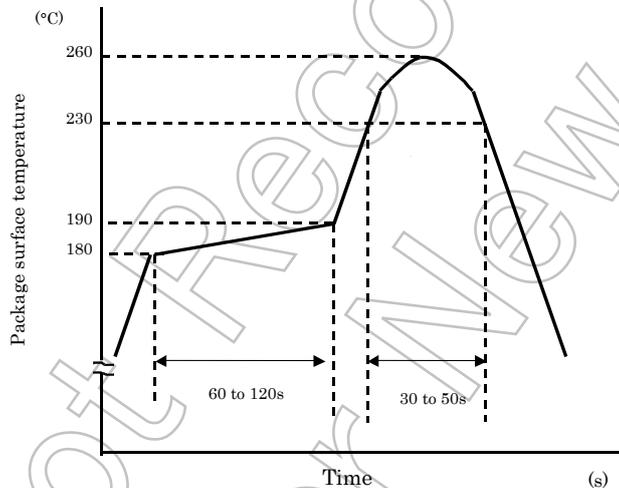
1) Using solder reflow

· Temperature profile example of lead (Pb) solder



This profile is based on the device's maximum heat resistance guaranteed value. Set the preheat temperature/heating temperature to the optimum temperature corresponding to the solder paste type used by the customer within the described profile.

· Temperature profile example of using lead (Pb)-free solder



This profile is based on the device's maximum heat resistance guaranteed value. Set the preheat temperature/heating temperature to the optimum temperature corresponding to the solder paste type used by the customer within the described profile.

Reflow soldering must be performed once or twice.

The mounting should be completed with the interval from the first to the last mountings being 2 weeks.

2) Using solder flow (for lead (Pb) solder, or lead (Pb)-free solder)

- Please preheat it at 150°C between 60 and 120 seconds.
- Complete soldering within 10 seconds below 260°C. Each pin may be heated at most once.

3) Using a soldering iron

Complete soldering within 10 seconds below 260°C, or within 3 seconds at 350°C. Each pin may be heated at most once.

2. Storage

- 1) Avoid storage locations where devices may be exposed to moisture or direct sunlight.
- 2) Follow the precautions printed on the packing label of the device for transportation and storage.
- 3) Keep the storage location temperature and humidity within a range of 5°C to 35°C and 45% to 75%, respectively.
- 4) Do not store the products in locations with poisonous gases (especially corrosive gases) or in dusty conditions.
- 5) Store the products in locations with minimal temperature fluctuations. Rapid temperature changes during storage can cause condensation, resulting in lead oxidation or corrosion, which will deteriorate the solderability of the leads.
- 6) When restoring devices after removal from their packing, use anti-static containers.
- 7) Do not allow loads to be applied directly to devices while they are in storage.
- 8) If devices have been stored for more than two years under normal storage conditions, it is recommended that you check the leads for ease of soldering prior to use.

Not Recommended
for New Design

Embossed-Tape Packing (TP) Specification for Mini-Flat Couplers

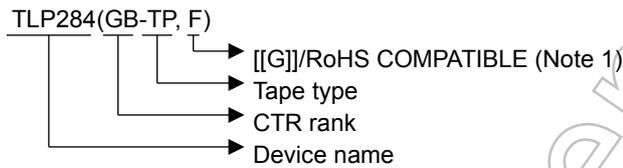
1. Applicable Package

Package	Product Type
SOP4	Mini-Flat Coupler

2. Product Naming System

Type of package used for shipment is denoted by a symbol suffix after a product number. The method of classification is as below.

(Example)



Note 1: Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS compatibility of Product.

The RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

3. Tape Dimensions

3.1 Orientation of Device in Relation to Direction of Tape Movement

Device orientation in the recesses is as shown in Figure 2.

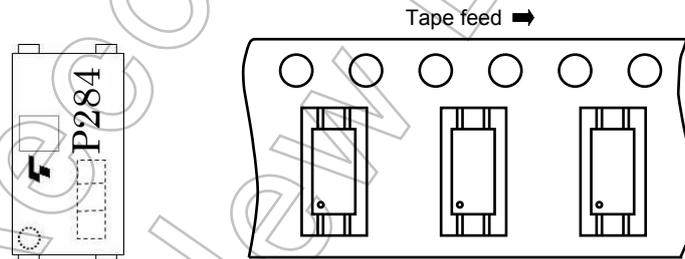


Figure 2 Device Orientation

3.2 Tape Packing Quantity: 2500 devices per reel

3.3 Empty Device Recesses Are as Shown in Table 1.

Table 1 Empty Device Recesses

	Standard	Remarks
Occurrences of 2 or more successive empty device recesses	0 device	Within any given 40-mm section of tape, not including leader and trailer
Single empty device recesses	6 device (max) per reel	Not including leader and trailer

3.4 Start and End of Tape

The start of the tape has 50 or more empty holes. The end of tape has 50 or more empty holes and two empty turns only for a cover tape.

3.5 Tape Specification

- (1) Tape material: Plastic (protection against electrostatics)
- (2) Dimensions: The tape dimensions are as shown in Figure 3 and table 2.

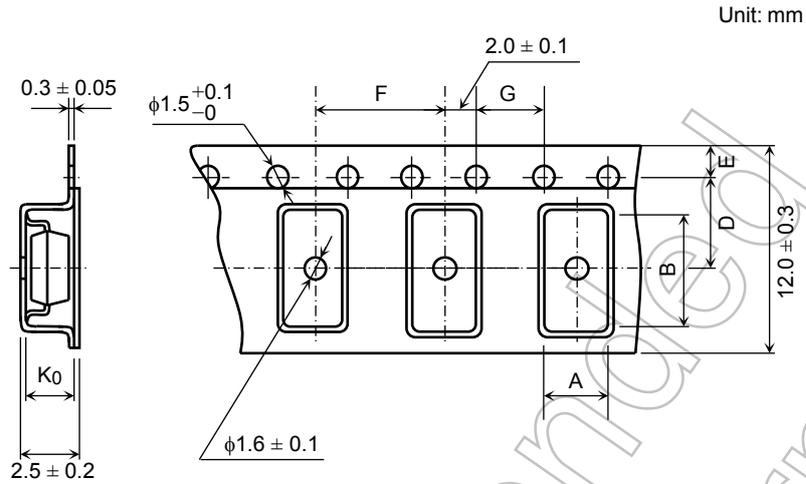


Figure 3 Tape Forms

Table 2 Tape Dimensions

Unit: mm
Unless otherwise specified: ±0.1

Symbol	Dimension	Remark
A	3.1	—
B	7.5	—
D	5.5	Center line of indented square hole and sprocket hole
E	1.75	Distance between tape edge and hole center
F	8.0	Cumulative error $\begin{matrix} +0.1 \\ -0.3 \end{matrix}$ (max) per 10 feed holes
G	4.0	Cumulative error $\begin{matrix} +0.1 \\ -0.3 \end{matrix}$ (max) per 10 feed holes
K0	2.3	Internal space

3.6 Reel

- (1) Material: Plastic
- (2) Dimensions: The reel dimensions are as shown in Figure 4 and Table 3.

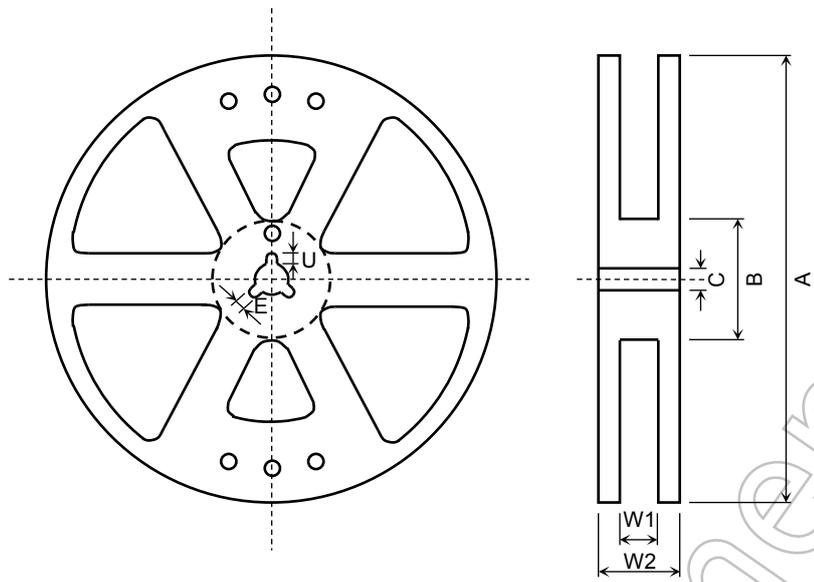


Figure 4 Reel Form

Table3 Reel Dimensions

Unit: mm

Symbol	Dimension
A	$\Phi 330 \pm 2$
B	$\Phi 80 \pm 1$
C	$\Phi 13 \pm 0.5$
E	2.0 ± 0.5
U	4.0 ± 0.5
W1	13.5 ± 0.5
W2	17.5 ± 1.0

4. Packing

Packed in a shipping carton.

5. Label Indication

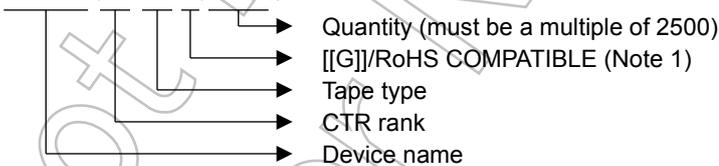
The carton bears a label indicating the product number, the symbol representing classification of standard, the quantity, the lot number and the Toshiba company name.

6. Ordering Method

When placing an order, please specify the product number, the CTR rank, the tape type and the quantity as shown in the following example.

Example)

TLP284(GB-TP, F) 2500 pcs.



Note 1: Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS compatibility of Product.

The RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

Insulation Related Specifications

Minimum creepage distance	Cr	5.0 mm
Minimum clearance	Cl	5.0 mm
Minimum insulation thickness	ti	0.4 mm
Comparative tracking index	CTI	175

Note: If a printed circuit is incorporated, the creepage distance and clearance may be reduced below this value. If this is not permissible, the user shall take suitable measures.

Note: This photocoupler is suitable for 'safe electrical isolation' only within the safety limit data. Maintenance of the safety data shall be ensured by means of protective circuit.

VDE test sign:



Marking on packing:



Marking Example:

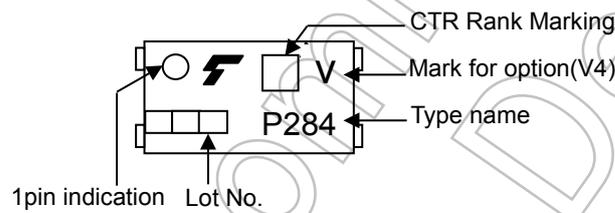


Figure 1 Partial discharge measurement procedure according to EN 60747
Destructive test for qualification and sampling tests.

Method A

(for type and sampling tests,
destructive tests)

- t_1, t_2 = 1 to 10 s
- t_3, t_4 = 1 s
- t_p (Measuring time for partial discharge) = 10 s
- t_b = 12 s
- t_{ini} = 60 s

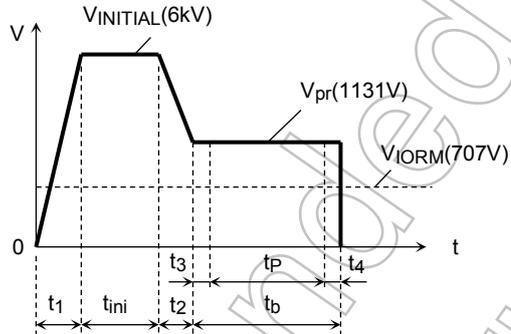


Figure 2 Partial discharge measurement procedure according to EN 60747
Non-destructive test for 100% inspection.

Method B

(for sample test, non-destructive test)

- t_3, t_4 = 0.1 s
- t_p (Measuring time for partial discharge) = 1 s
- t_b = 1.2 s

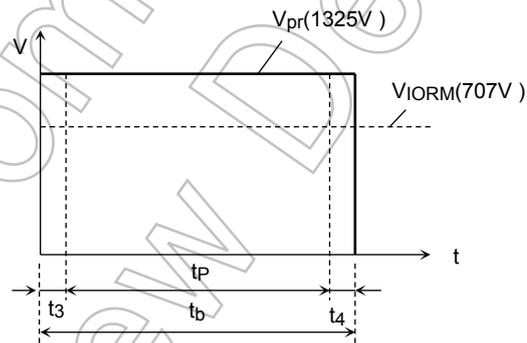
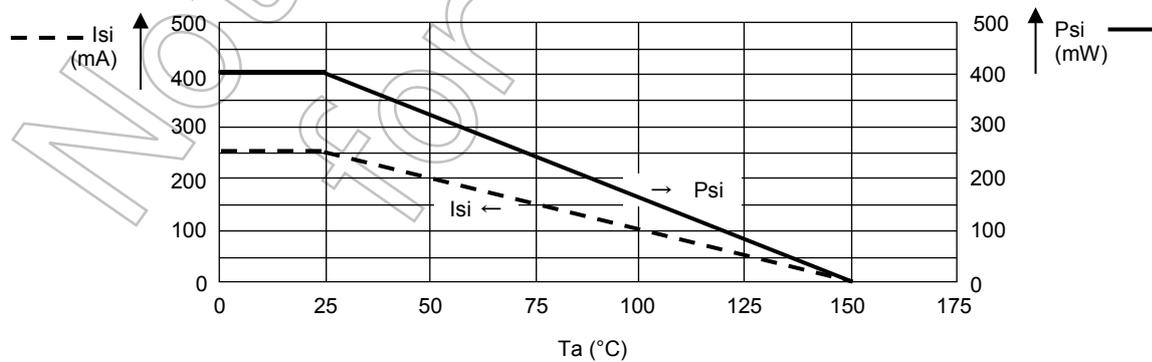


Figure 3 Dependency of maximum safety ratings on ambient temperature



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